

LEAD FRAME CHIP SCALE PACKAGE

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ABSTRACT

A method for producing chip scale IC packages includes the step of mounting a lead frame panel on a temporary support fixture in order to provide support and protection during the manufacturing process. An embodiment of the temporary support fixture includes a sheet of sticky tape secured to a rigid frame. The rigid frame maintains tension in the sheet of sticky tape to provide a stable surface to which the lead frame panel can be affixed. Installation of IC chips and encapsulation in protective casings is performed as in conventional IC package manufacturing. If encapsulant material is to be dispensed over the IC chips, an encapsulant dam can be formed around the lead frame panel to contain the flow of encapsulant material. The temporary support fixture can be used in any IC package manufacturing process in which lead frames require supplemental support.

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